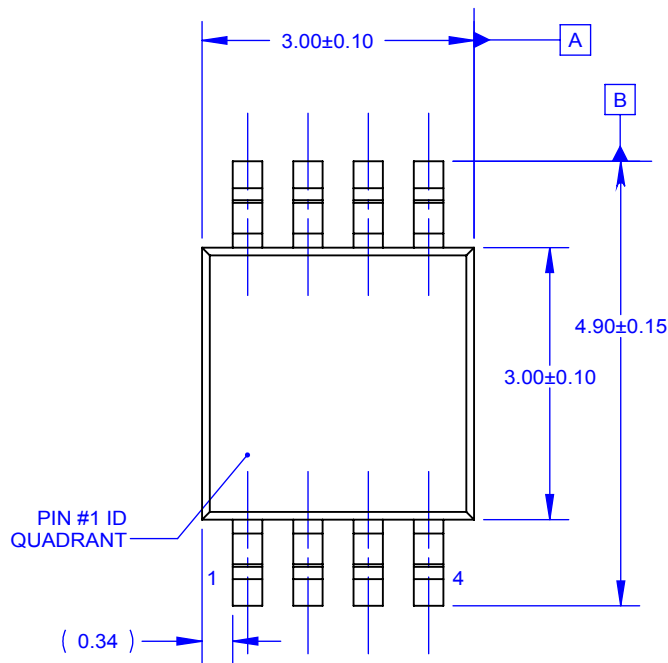
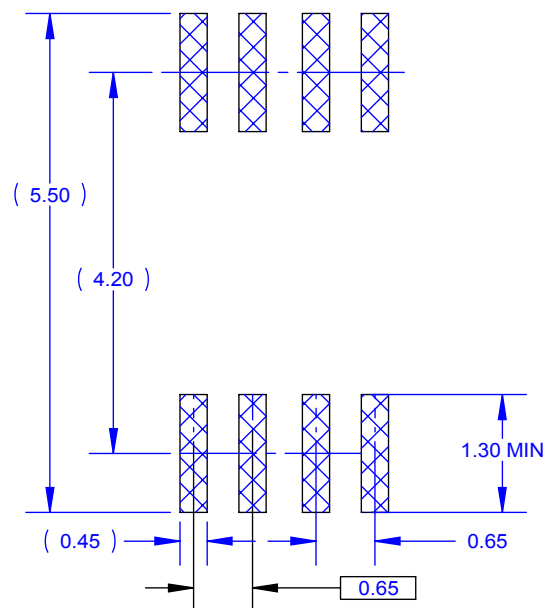


REVISIONS

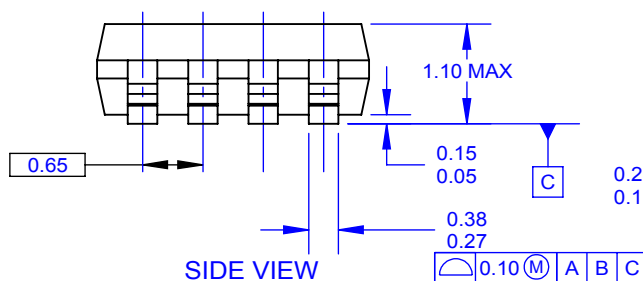
NBR	DESCRIPTION	DATE	BY/APP'D
B	REDREW FORMER NSC DWG	07JUN2006	H.ALLEN
3	* REMOVE SITE ADDRESS AND CHANGE REVISION TO NUMERICAL. * CHANGE LEAD WIDTH FROM 0.27-0.38 TO 0.22-0.40. * CHANGE STAND OFF FROM 0.05MIN TO 0.00MIN. * CHANGE LEAD THICKNESS FROM 0.13MIN TO 0.08MIN. * CHANGE FOOT LENGTH FROM 0.70MAX TO 0.80MAX.	20AUG2009	KHLEE/FSSZ
4	* REVERT LEAD WIDTH TO PREV REV 0.27-0.38. * REVERT STAND OFF TO 0.05MIN. * REVERT LEAD THICKNESS TO 0.13MIN. * REVERT FOOT LENGTH TO 0.70MAX.	24SEP2009	KHLEE/FSSZ



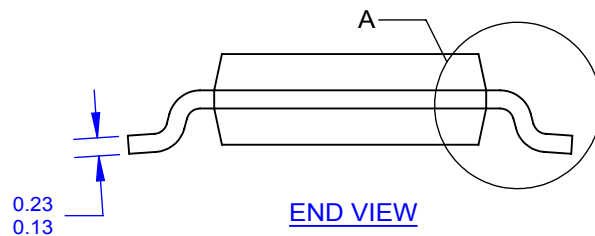
TOP VIEW



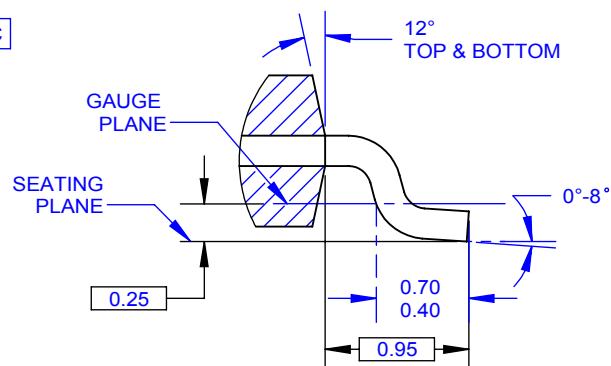
LAND PATTERN RECOMMENDATION



SIDE VIEW



END VIEW



DETAIL A
SCALE 20 : 1

NOTES: UNLESS OTHERWISE SPECIFIED

- THIS PACKAGE CONFORMS TO JEDEC MO-187.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- DIMENSIONS AND TOLERANCES AS PER ASME Y14.5-1994.
- LAND PATTERN AS PER IPC7351#TSOP65P490X110-8BL
- FILE NAME: MKT-MUA08AREV4

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR		
DRAWN: BOBOY MALDO	24SEP09			
CHECKED: KH LEE		8LD, MSOP, JEDEC MO-187, 3.0MM WIDE		
APPROVED: BY HUANG				
APPROVED: HOWARD ALLEN				
PROJECTION		SCALE 1:1	SIZE N/A	DRAWING NUMBER MKT-MUA08A
				REV 4
			FORMERLY: N/A	SHEET: 1 OF 1